IPC  ASSOCIATION CONNECT ELECTRONICS INDUSTI	© Copyright 2005. IPG	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mf	g Information	on		
upplier Infor	mation													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2024-05-18				
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Ste	wards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized Repre	esentative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Reque	ster Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	ersion Manufacturing Site		V	Veight*	UOM	Unit Type
	US1GFA HER SOD123		HER SOD123FA G	FA GPPN 1A 400V		2024-05-18	D5-18 TSCBE		1	8.79156	mg	Each		
	g Process Informati		arminal Paga	Alloy	STD-020 MSL	Pating	Dook Proo	oge Pody T	amparatur	e Max Time at Peak	Tamparati	uro Numbe	er of Reflow Cyc	alac
			Terminal Base Alloy J-ST CU Alloy 1		51D-020 MSL	. Kaung	260	cess Body Temperature   Max Time at Peak		seconds 3		er of Reflow Cyc	nes	
•	ım (ən) - anneaied	C	U Alloy	1			200		IC	30	second	18 3		
omments	. time at neals townt	o dunina1	domina ia 10.7	20 seconds										
	n time at peak temperatur													
r more informa	ition regarding material c	omposition j	piease reter t	o page 3										

<b>RoHS Material Composition Declaration</b>			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of the supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warran											
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).  Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature R		,									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.72998	mg	Supplier	Silicon (Si)	7440-21-3		0.657	mg
			В	Nickel (Ni)	7440-02-0		0.0047	mg
			Supplier	Gold (Au)	7440-57-5		0.0011	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0672	mg
Die Attach Solder	4.11996	mg	Supplier	Silver (Ag)	7440-22-4		0.103	mg
			A	Lead (Pb)	7439-92-1	7a	3.811	mg
			Supplier	Tin (Sn)	7440-31-5		0.206	mg
Lead Frame	6.79991	mg	Supplier	Iron (Fe)	7439-89-6		0.0068	mg
			Supplier	Copper (Cu)	7440-50-8		6.7911	mg
			Supplier	Phosphorus (P)	7723-14-0		0.002	mg
Mold Compound-Black	6.94164	mg		Metal Hydroxide	proprietary data		0.3471	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0694	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.2062	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.6942	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.6247	mg
Plating	0.20007	mg	Supplier	Tin (Sn)	7440-31-5		0.2001	mg